



## Surge arrester

2-electrode arrester

<b>Series/Type:</b>	<b>S30-A420XS</b>
<b>Ordering code:</b>	<b>B88069X6311T203</b>
Date:	2019-04-10
Version:	03


**Features**

- Very small size (EIA 1812)
- Short response time
- High current capability
- Stable performance over service life
- Ultra low capacitance and insertion loss
- High insulation resistance
- Excellent SMD handling
- RoHS-compatible

**Applications**

- PCI cards
- Modem
- Splitter
- Line cards
- Applications with limited space

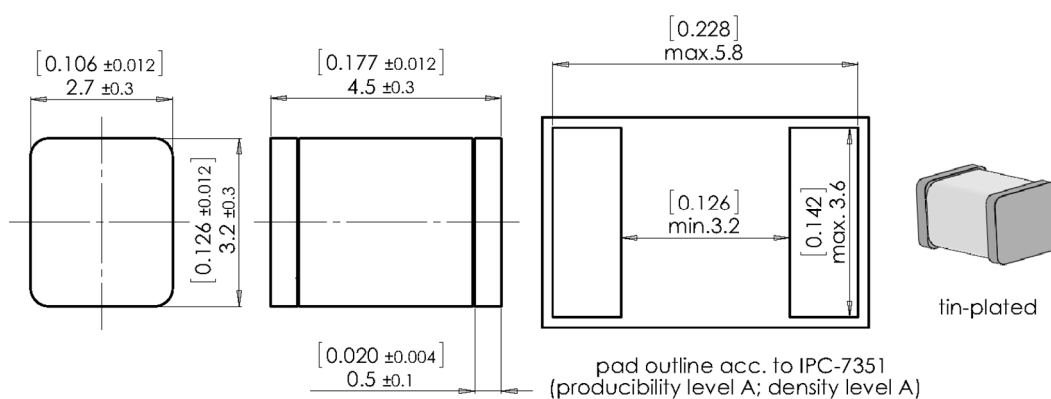
**Electrical specifications and stress test methods**

Nominal DC spark-over voltage <sup>1) 2)</sup>	420	V
Tolerance	±25	%
Min.	315	V
Max.	525	V
Impulse spark-over voltage		
at 100 V/μs	- for 99% of measured values - typical values of distribution	< 650 < 550
at 1 kV/μs	- for 99% of measured values - typical values of distribution	< 750 < 600
Service life <sup>3) 4)</sup>		
300 operations	8/20 μs	100
10 operations [5x (+) & 5x (-)]	8/20 μs	1
100 operations [50x (+) & 50x (-)]	10/1000 μs	10
Insulation resistance at 100 V <sub>DC</sub>	> 1	GΩ
Capacitance at 1 MHz	< 0.8	pF
Arc voltage at 1 A	~ 20	V
Glow to arc transition current	< 0.3	A
Glow voltage	~ 150	V
Weight	~ 0.2	g
Operation and storage temperature	-40 ... +125	°C
Climatic category (IEC 60068-1)	40/125/ 21	
Marking, black positive	 L - Nominal voltage (L ≙ 420 V) Y - Year of production (last digit)	
Remarks on next page		

- 1) At delivery AQL 0.65 level II, DIN ISO 2859
- 2) In ionized mode
- 3) Tests according to ITU-T Rec. K. 12 and UL 497B
- 4) Data after Service life:
  - DC spark-over voltage 420 V  $\pm$ 30%
  - Impulse spark-over voltage at 100 V/ $\mu$ s < 850 V
  - Impulse spark-over voltage at 1 kV/ $\mu$ s < 1000 V
  - Insulation resistance IR > 10<sup>8</sup> Ohm

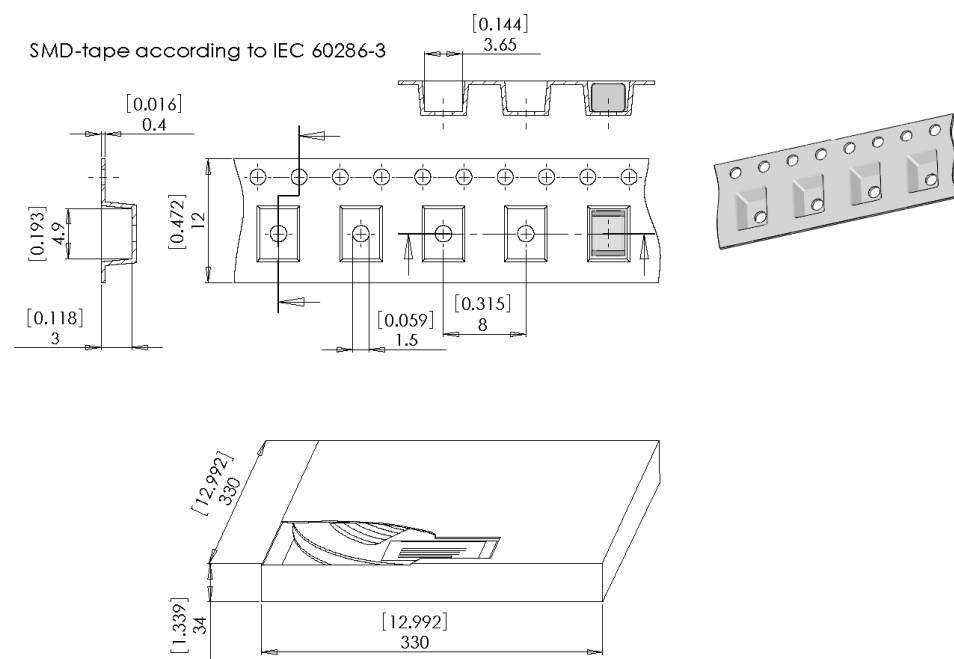
Terms and current waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21 and IEC 61643-311.

### Dimensions in mm and inch [...]



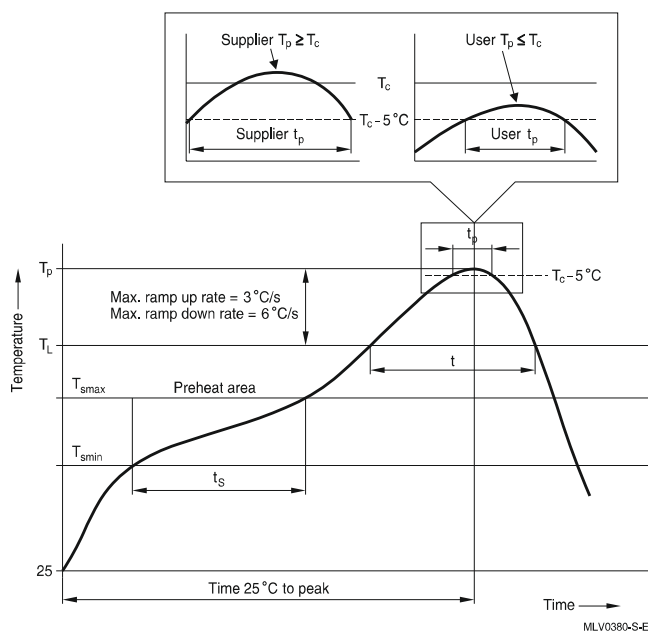
### Ordering code and packing advice

**B88069X6311T203** = 2000 pcs. on SMD-tape & reel



## Soldering parameter

### Reflow soldering



Reflow profile features		Sn- Pb eutectic assembly	Pb-free assembly
Preheat and soak - Temperature min - Temperature max - Time	$T_{smin}$ $T_{smax}$ $t_{smin}$ to $t_{smax}$	100 °C 150 °C 60 ... 120 s	150 °C 200 °C 60 ... 180 s
Average ramp-up rate	$T_{smax}$ to $T_p$	max. 3 °C/ s	max. 3 °C/ s
Liquidous temperature Time at liquidous	$T_L$ $t_L$	183 °C 60 ... 150 s	217 °C 60 ... 150 s
Peak package body temperature *, Classification temperature **	$T_p$ , $T_c$	220 ... 235 °C **	245 ... 260 °C **
Time ( $t_p$ ) ** within 5 °C of the specified classification temperature ( $T_c$ )		20 s ***	30 s ***
Average ramp-down rate	$T_p$ to $T_{smax}$	max. 6 °C/ s	max. 6 °C/ s
Time 25 °C to peak temperature		max. 6 min	max. 8 min

\* = Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.  
 \*\* = For details please refer to JEDEC J-STD-020D.  
 \*\*\* = Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.

Surface mounted components (SMD) may exhibit a temporary increase in the DC spark-over voltage after the solder reflow process. The components will recover within 24 hours. There is no quality defect nor change in protection levels during the temporary change in DC spark-over voltage.

## Cautions and warnings

- Do not operate surge arresters in power supply networks, whose maximum operating voltage exceeds the minimum spark-over voltage of the surge arresters.
- Surge arresters may become hot in the event of longer periods of current stress (burn risk). In the event of overload the connectors may fail or the component may be destroyed.
- Surge arresters must be handled with care and must not be dropped.
- Do not continue to use damaged surge arresters.
- The shown SMD pad dimensions represent a safe way to mount the arrester and are a recommendation of the manufacturer. During the reflow process it must be assured that no solder material reduces the insulation distance between the pads below the arrester.
- SMD surge arresters should be soldered within 24 month after shipment.

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## Important notes

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